MBR130T1, MBR130T3

Surface Mount Schottky Power Rectifier

Plastic SOD-123 Package

This device uses the Schottky Barrier principle with a large area metal—to—silicon power diode. Ideally suited for low voltage, high frequency rectification or as free wheeling and polarity protection diodes in surface mount applications where compact size and weight are critical to the system. This package also provides an easy to work with alternative to leadless 34 package style.

Features

- · Guardring for Stress Protection
- Low Forward Voltage
- 125°C Operating Junction Temperature
- Epoxy Meets UL 94 V-0 @ 0.125 in
- Package Designed for Optimal Automated Board Assembly
- ESD Ratings: Machine Model, C; Human Body Model, 3
- Pb-Free Packages are Available

Mechanical Characteristics

- Reel Options: MBR130T1 = 3,000 per 7 in reel/8 mm tape MBR130T3 = 10,000 per 13 in reel/8 mm tape
- Device Marking: S3
- Polarity Designator: Cathode Band
- Weight: 11.7 mg (approximately)
- Case: Epoxy, Molded
- Finish: All External Surfaces Corrosion Resistant and Terminal Leads are Readily Solderable
- Lead and Mounting Surface Temperature for Soldering Purposes: 260°C Max. for 10 Seconds



ON Semiconductor®

SCHOTTKY BARRIER RECTIFIER 1.0 AMPERES 30 VOLTS



SOD-123 CASE 425 STYLE 1

MARKING DIAGRAM



S3 = Specific Device Code

M = Date Code

= Pb–Free Package

(Note: Microdot may be in either location)

ORDERING INFORMATION

Device	Package	Shipping [†]		
MBR130T1	SOD-123	3000/Tape & Reel		
MBR130T1G	SOD-123 (Pb-Free)	3000/Tape & Reel		
MBR130T3	SOD-123	10,000/Tape & Reel		
MBR130T3G	SOD-123 (Pb-Free)	10,000/Tape & Reel		

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

MBR130T1, MBR130T3

MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V _{RRM} V _{RWM} V _R	30	V
Average Rectified Forward Current (Rated V_R) $T_L = 65^{\circ}C$	I _{F(AV)}	1.0	А
Non-Repetitive Peak Surge Current (Surge Applied at Rated Load Conditions, Halfwave, Single Phase, 60 Hz)	I _{FSM}	5.5	А
Storage Temperature Range	T _{stg}	-65 to +125	°C
Operating Junction Temperature	TJ	-65 to +125	°C
Voltage Rate of Change (Rated V _R)	dv/dt	1000	V/µs

THERMAL CHARACTERISTICS

Characteristic	Symbol	Value	Unit
Thermal Resistance, Junction to Ambient (Note 1)	$R_{\theta JA}$	230	°C/W
Thermal Resistance, Junction to Lead (Note 1)	$R_{\theta JL}$	108	°C/W

Maximum ratings are those values beyond which device damage can occur. Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and are not valid simultaneously. If these limits are exceeded, device functional operation is not implied, damage may occur and reliability may be affected.

1. FR-4 or FR-5 = 3.5 × 1.5 inches using a 1 inch Cu pad.

ELECTRICAL CHARACTERISTICS

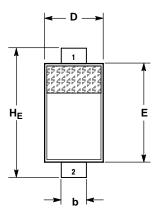
Characteristic	Symbol	Тур	Max	Unit
Maximum Instantaneous Forward Voltage (Note 2)	V_{F}			V
$(I_F = 0.1 \text{ A}, T_J = 25^{\circ}\text{C})$		_	0.35	
$(I_F = 0.7 \text{ A}, T_J = 25^{\circ}\text{C})$		_	0.45	
$(I_F = 1.0 \text{ A}, T_J = 25^{\circ}\text{C})$		0.47	_	
Maximum Instantaneous Reverse Current (Note 2)	I _R			μΑ
(Rated DC Voltage, T _C = 25°C)		6	0	
$(V_R = 5 \text{ V}, T_C = 25^{\circ}\text{C})$		1	0	

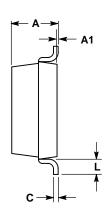
^{2.} Pulse Test: Pulse Width = 300 μ s, Duty Cycle \leq 2%.

MBR130T1, MBR130T3

PACKAGE DIMENSIONS

SOD-123 CASE 425-04 **ISSUE E**



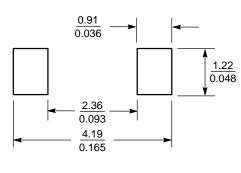


- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: INCH.

	MILLIMETERS			INCHES		
DIM	MIN	NOM	MAX	MIN	NOM	MAX
Α	0.94	1.17	1.35	0.037	0.046	0.053
A1	0.00	0.05	0.10	0.000	0.002	0.004
b	0.51	0.61	0.71	0.020	0.024	0.028
С			0.15		-	0.006
D	1.40	1.60	1.80	0.055	0.063	0.071
E	2.54	2.69	2.84	0.100	0.106	0.112
HE	3.56	3.68	3.86	0.140	0.145	0.152
	0.25			0.010		

STYLE 1: PIN 1. CATHODE 2. ANODE

SOLDERING FOOTPRINT*



(mm/inches) SCALE 10:1

^{*}For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.